

B1
cond

anhydride-ethyl acrylate copolymer, graft copolymer of ethylene -glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene -glycidyl methacrylate-ethylene ethyl acrylate copolymer.

B2

3. (Amended) The resin molded component according to Claim 1, wherein the elastic material is present in an amount of from 0.5 to 10 parts in mass to 100 parts in mass of said base resin.

4. (Amended) The resin molded component according to Claim 1, wherein said base resin comprises at least one member selected from the group consisting of polyphthalamide and polyphenylene sulfide.

5. (Amended) The resin molded component according to Claim 1, wherein said resin composition further comprises an inorganic filler.

6. (Amended) The resin molded component according to Claim 5, wherein said inorganic filler is fibrous having a diameter of from 0.5 to 5 μm and a length of from 10 to 50 μm .

7. (Amended) The resin molded component according to Claim 5, wherein said inorganic filler is plate-form.

8. (Amended) The resin molded component according to Claim 5, wherein said inorganic filler is a combination of a fiber form having a diameter of from 0.5 to 5 μm and a

length of from 10 to 50 μm with a plate-form inorganic filler.

B²
cond
9. (Amended) The resin molded component according to Claim 5, wherein said inorganic filler is spherical.

10. (Amended) The resin molded component according to Claim 5, wherein said inorganic filler is present in an amount of from 40 to 75% in mass with respect to said whole resin composition.

11. (Amended) A printed circuit board, comprising the resin molded component according to Claim 1.--

Please add the following claims.

B³
--12. (New) The resin molded component according to Claim 1, wherein said resin composition further comprises a plate-form inorganic filler comprising at least one member selected from the group consisting of talc, mica, glass flake, monmorillonite, and smectite.--

13. (New) The resin molded component according to Claim 1, wherein said elastic material comprises ethylene -glycidyl methacrylate-methyl acrylate copolymer.

14. (New) The resin molded component according to Claim 1, wherein said elastic material comprises ethylene-maleic anhydride-ethyl acrylate copolymer.

B³
cancel

15. (New) The resin molded component according to Claim 1, wherein said elastic material comprises graft copolymer of ethylene -glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer.

16. (New) The resin molded component according to Claim 1, wherein said elastic material comprises ethylene -glycidyl methacrylate-ethylene ethyl acrylate copolymer.--

SUPPORT FOR THE AMENDMENT

Claim 2 is cancelled. Claims 12-16 are added. Claims 1 and 3-11 are amended to place the claims in proper form. Further, Claim 1 is amended to include the embodiments of originally-filed Claim 2. Therefore, support for the amendment is found in the original claims. Finally, new Claim 12 is supported at page 11, lines 1-2, of the specification, and new Claims 13-16 are supported by original claims 1 and 2.